



Material Content Data Sheet



Sales Product Name	TLD5098EL			Issued		28. October 2019		
MA#	MA001927670							
Package	PG-SSOP-14-3			Weight*		83.09 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.131	2.57	2.57	25652	25652
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.689	0.83		8293	
	non noble metal	copper	7440-50-8	27.978	33.67	34.55	336725	345537
wire	noble metal	gold	7440-57-5	0.207	0.25	0.25	2487	2487
encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1193	
	plastics	epoxy resin	-	4.560	5.49		54884	
	inorganic material	silicondioxide	60676-86-0	44.908	54.05	59.66	540493	596570
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11748	11748
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9239	9239
glue	plastics	epoxy resin	-	0.182	0.22		2192	
	noble metal	silver	7440-22-4	0.546	0.66	0.88	6575	8767
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com